

Notice of References Cited	Application/Control No. 10/759,267		Applicant(s)/Patent Under Reexamination YUN ET AL.	
	Examiner Paresh Patel		Art Unit 2829	Page 1 of 1

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*	B	US-5,461,544	10-1995	Ewers, Charles R.	361/760
*	C	US-5,301,155	04-1994	Wada et al.	365/201
*	D	US-6,697,978	02-2004	Bear et al.	714/718
*	E	US-6,246,618	06-2001	Yamamoto et al.	365/200
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NON-PATENT DOCUMENTS

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	U	"Advanced Packaging" January 2003 pages 1-2 and 29-31 (total five pages)
	V	Economics modelling for the determination of optimal good die strategies" by C. Dislis Dept. of Cybernetics, Uni. of Reading, UK 0-8186-6970-5/94 1994 IEEE, PAGES 8-13.
	W	"MCM BURN-IN EXPERIENCE" BY Tom et al. IBM Microelectronics, MCM '94 Proceedings, pages 223-229
	X	"TESTABILITY CHALLENGES TO ACHIVE ZERO DEFECT GOAL IN MCM MANUFACTURING" BY David et al. of IBM, IEEE/CHMT '91 Symposium (CH3043-7/91/0000-0417 1991 IEEE), PAGES 417 AND 418.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.